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FQD5P10 P-Channel QFET[®] MOSFET

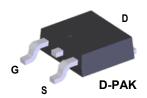
-100 V, -3.6 A, 1.05Ω

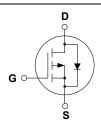
Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.



- -3.6 A, -100 V, R_{DS(on)} = 1.05 Ω (Max.) @ V_{GS} = -10 V, I_D = 1.8 A
- Low Gate Charge (Typ. 6.3 nC)
- Low Crss (Typ. 18 pF)
- · 100% avalanche tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter			FQD5P10	Unit
V _{DSS}	Drain-Source Voltage			-100	V
I _D	Drain Current	- Continuous (T _C = 25°C)		-3.6	А
		- Continuous (T _C = 10	0°C)	-2.28	Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	-14.4	Α
V _{GSS}	Gate-Source Vo	Itage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		(Note 2)	55	mJ
I _{AR}	Avalanche Current		(Note 1)	-3.6	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		(Note 3)	-6.0	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W	
	Power Dissipation (T _C = 25°C)			25	W
	- Derate above 25°C			0.2	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQD5P10	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	5.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	110	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-100			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-0.1		V/°C
I _{DSS}	7 0 1 1/1 5 1 0 1	V _{DS} = -100 V, V _{GS} = 0 V			-1	μА
	Zero Gate Voltage Drain Current	V _{DS} = -80 V, T _C = 125°C			-10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250 μA	-2.0		-4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	atic Drain-Source V _{CS} = -10 V, I _D = -1.8 A		0.82	1.05	Ω
9 _{FS}	Forward Transconductance $V_{DS} = -40 \text{ V}, I_D = -1.8 \text{ A}$			2.3		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$	-	190	250	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		70	90	pF
C _{rss}	Reverse Transfer Capacitance			18	25	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = -50 V, I _D = -4.5 A,		9	30	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		70	150	ns
t _{d(off)}	Turn-Off Delay Time	1.6 2012		12	35	ns
t _f	Turn-Off Fall Time	(Note 4)		30	70	ns
Qg	Total Gate Charge	V _{DS} = -80 V, I _D = -4.5 A,		6.3	8.2	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		1.7		nC
Q _{gd}	Gate-Drain Charge			3.0		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				-3.6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-14.4	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -3.6 \text{ A}$			-4.0	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = -4.5 A,		85		ns
Q _{rr}	Reverse Recovery Charge dI _F / dt = 100 A/μs			0.27		μС

Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 6.4mH, I $_{AS}$ = -3.6A, V $_{DD}$ = -25V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C 3. $_{SD}$ \leq -4.5A, di/dt \leq 300A/ $_{J}$ s, V $_{DD}$ \leq BV $_{DSS}$, Starting T $_{J}$ = 25°C 4. Essentially independent of operating temperature

Typical Characteristics

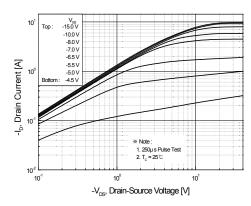


Figure 1. On-Region Characteristics

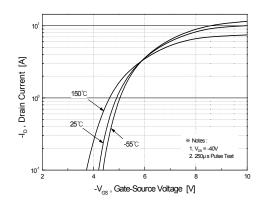


Figure 2. Transfer Characteristics

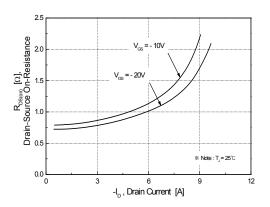


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

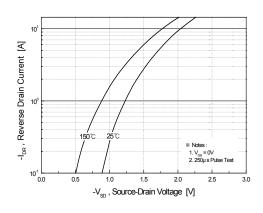


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

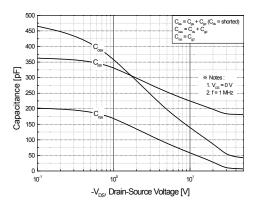


Figure 5. Capacitance Characteristics

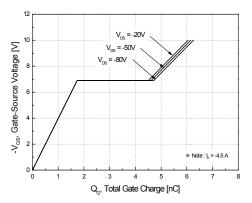
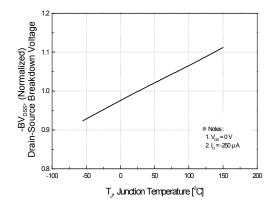


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)



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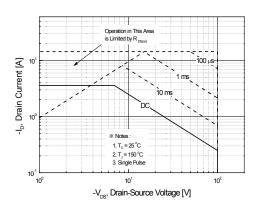
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Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



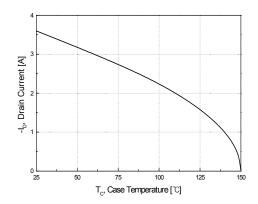


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

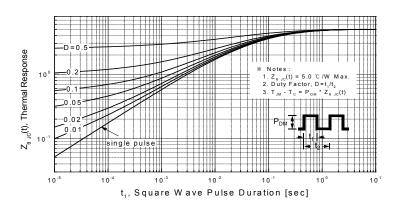
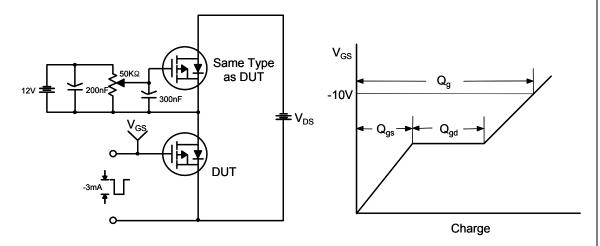
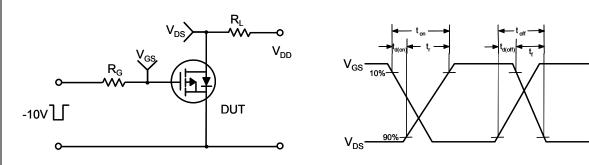


Figure 11. Transient Thermal Response Curve

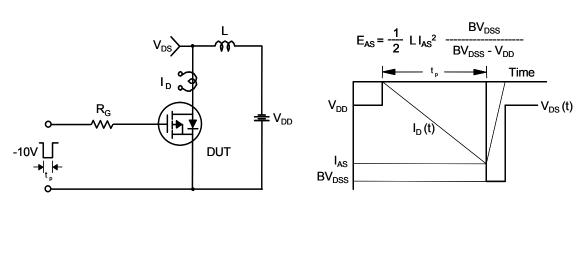
Gate Charge Test Circuit & Waveform



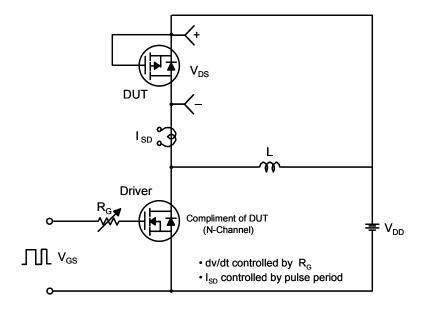
Resistive Switching Test Circuit & Waveforms

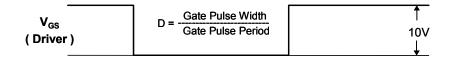


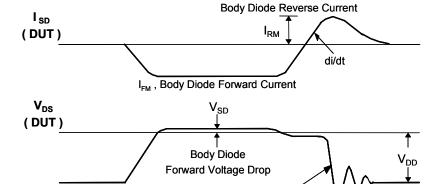
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



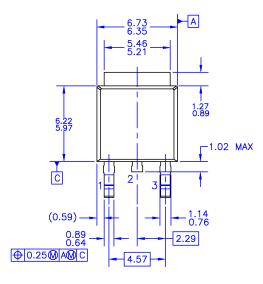


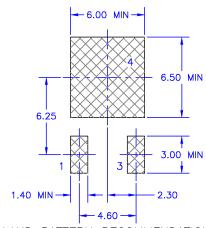


Body Diode Recovery dv/dt

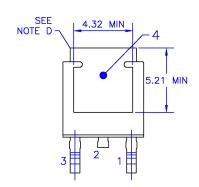
Package Dimensions

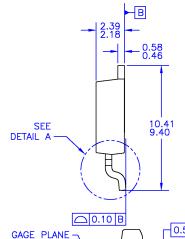
D-PAK





LAND PATTERN RECOMMENDATION





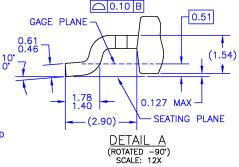
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 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M-1994.

 D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
 E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.
 F) DIMENSIONS ARE EXCLUSSIVE OF BURSS, MOLD FLASH AND TIE BAR EXTRUSIONS.
 G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD TO220P1003X238-3N.
 H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV8

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Dimensions in Millimeters





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